



**cadcam-e<sup>sm</sup>**

Your Partner in Engineering Information Technology

BY OVERNIGHT MAIL and ELECTRONIC FAX

Moldflow Corporation  
Attn: Lori M. Henderson  
430 Boston Post Road  
Wayland, MA 01778-1824  
USA

**Ref: Patent Application # 09/844,466 filed by Moldflow Corporation**

Dear Ms. Henderson:

Pursuant to our conversation on October 3, 2002 regarding the subject matter above, I recap below the main points of our discussion. As I mentioned during our conversation, CADCAM-E.COM's goal is to reach an amicable settlement with Moldflow at the earliest regarding the continued use of our technology in our products and services, thus avoiding any legal or financial entanglements.

Our position can be summarized as follows: CADCAM-E.COM has identified four options that we can pursue to reach a settlement on this issue.

**Option #1:** Any overlap in technology is completely coincidental and the two parties were developing the technologies almost simultaneously and totally independently from each other. If a joint, detailed technical analysis reveals that some portions of our licensing scheme appear to be substantially similar to portions of Moldflow's licensing scheme, Moldflow shall certify CADCAM-E's scheme to be non-infringing on its technology OR offer CADCAM-E its licensing technology on a free, non-exclusive basis. In return, CADCAM-E shall acknowledge the validity of Moldflow's patent application by not filing a protest with the USPO.

**Option #2:** If a detailed technical analysis reveals minimal overlap between CADCAM-E's and Moldflow's technologies, CADCAM-E may offer to undertake reasonable efforts, with Moldflow's help and guidance, to make its technology non-infringing. Moldflow, then, shall certify our scheme to be non-infringing.

**Option #3:** If a detailed technical analysis reveals minimal overlap, CADCAM-E and Moldflow shall jointly conclude that the two licensing schemes are substantially different. Moldflow shall further acknowledge that CADCAM-E is free to continue to use its own technology, and abrogate any and all claims, even after the patent is awarded.

**Option #4:** CADCAM-E shall file an interested-party protest with the US Patent Office against awarding the above patent to Moldflow Corporation. CADCAM-E made its technology public in June/July 2000, well before Moldflow applied for the patent.


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NEW JERSEY OFFICE: 6 Arrow Road, Suite 208 • Ramsey, NJ 07446 U.S.A. • (201) 995-9285 • Fax: (201) 995-9283  
Website: [www.cadcam-e.com](http://www.cadcam-e.com) • Email: [sales@cadcam-e.com](mailto:sales@cadcam-e.com)

Subsequent to your letter dated September 25, 2002 and our telephone conversation on October 3, 2002, and numerous telephone messages to your offices between October 3 and today, we have not been successful in our attempts at contacting the appropriate personnel at Moldflow to discuss and perhaps settle the issue.

CADCAM-E therefore has to conclude that Moldflow lack of reciprocity to discuss the issue with CADCAM-E after repeated offers demonstrates its intent to enforce the above patent when awarded. Therefore, CADCAM-E shall have no alternative but to pursue legal avenues if Moldflow opts not to reply to this written notice inviting it for discussion within 7 business days.

I can be reached at (201) 995 9285.

Yours truly,

 October 24, 2002.

Kumar Rajan  
Chief Executive Officer  
CADCAM-E.COM Inc.

cc: DSD

**Moldflow Corporation**

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USA

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www.moldflow.com  
www.plasticszone.com

September 25, 2002

BY OVERNIGHT MAIL

CADCAM-E.COM, Inc.  
Attn: President  
28124 Orchard Lake Road  
Suite 101  
Farmington Hills, MI

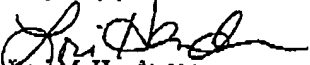
Re: CADCAM-E.COM Services

Dear Sir or Madam:

As you may be aware, Moldflow Corporation has filed a United States patent application on our invention entitled "Network Enabled Application Software System and Method." This patent application was filed in the United States on April 27, 2001 and was published on February 7, 2002. The application number is 09/844,466 and a copy is enclosed for your reference. Moldflow has also filed an International Patent Application under the Patent Cooperation Treaty, which was filed on April 27, 2001, with a priority date of April 28, 2000. The International Application Number is PCT/US01/13427 and it was published on November 8, 2001. A copy is enclosed for your reference. We will nationalize the International Application shortly.

We have recently become aware of your product, CADCAM-E.COM. We have reviewed the product description available on your web site, [www.cadcam-e.com](http://www.cadcam-e.com). Your product seems to employ technology similar to that described in our pending patent applications. The purpose of this letter is to ~~insure that you are aware of our pending patent applications and to invite you to discuss with us your use of~~ this technology. We look forward to hearing back from you in the near future.

Very truly yours,

  
Lori M. Henderson  
General Counsel

Cc: Roland Thomas  
Ken Welch